



Title of Change:	SEMCO substrates supplier Discontinuance – Qualification of Alternate supplier.							
Proposed first ship date:	1 January 2019							
Contact information:	Contact your local ON Semiconductor Sales Office or < ivo.rotthier@onsemi.com > or < Renato.NeypesJr@onsemi.com >							
Samples:	Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.							
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < phine.guevarra@onsemi.com >							
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < PCN.Support@onsemi.com >							
Change Part Identification:	Affected products will be identified by date code							
Change Category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____							
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____							
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: Amkor Technology Philippines P3						
Description and Purpose:								
This Final Change Notification announces the qualification of a new lead frame supplier, UMTC and Nanya substrate for ATP3 LFBGA products, at Amkor Technology Philippines Plant 3 for orderable part number, 0W888-002-XTP. Change also includes from Halogenated (HL832/AUS308) to non-Halogenated materials (HL832NXA/AUS308). This change is due to the substrate supplier Semco Tenting CSP discontinuance. This will allow more flexibility on lead frame management and prevent lead frame shortage issues.								
<table border="1" style="width: 100%; text-align: center;"> <thead> <tr style="background-color: #92d050;"> <th>Material to be changed</th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Leadframe</td> <td>SAMSUNG HL832/AUS308</td> <td>NANYA HL832NXA/AUS308 UMTC HL832NXA/AUS308</td> </tr> </tbody> </table>			Material to be changed	Before Change Description	After Change Description	Leadframe	SAMSUNG HL832/AUS308	NANYA HL832NXA/AUS308 UMTC HL832NXA/AUS308
Material to be changed	Before Change Description	After Change Description						
Leadframe	SAMSUNG HL832/AUS308	NANYA HL832NXA/AUS308 UMTC HL832NXA/AUS308						

**Reliability Data Summary:**

QV DEVICE NAME: 0W888-02

RMS: O42835, O42622

PACKAGE: LFBGA 64

Nanya

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1000 hrs	0/240
TC	JESD22-A104	Ta= -55°C to +125°C	1000 cyc	0/240
uHAST	JESD22-A118	110°C, 85% RH, 18.8psig, unbiased	264 hrs	0/237
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C		0/480
SBS	AEC-Q100-010			0/30
PD	JESD22-B100, B108			0/30

UMTC – Unimicron Technology Corporation

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1000 hrs	0/239
TC	JESD22-A104	Ta= -55°C to +125°C	1000 cyc	0/238
uHAST	JESD22-A118	110°C, 85% RH, 18.8psig, unbiased	264 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C		0/474
SBS	AEC-Q100-010			0/30
PD	JESD22-B100, B108			0/30

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Part:

Part Number	Qualification Vehicle
0W888-002-XTP	0W888-002-XTP